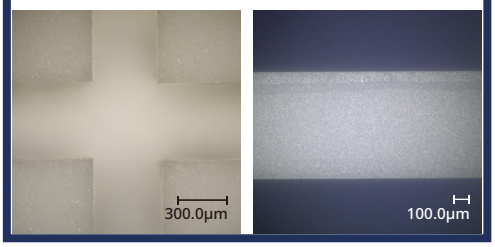
Cutting samples with "Wheel Scribe & Break"

Bare substrates

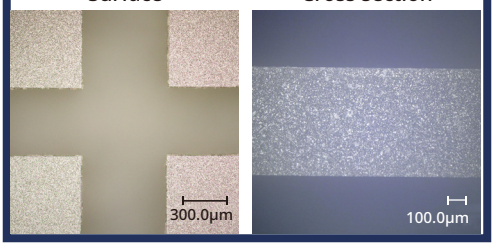
Material	: Al_2O_3
Thickness	: t0.635 mm
Substrate size	: 100 mm x 100 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

Surface / Cross section



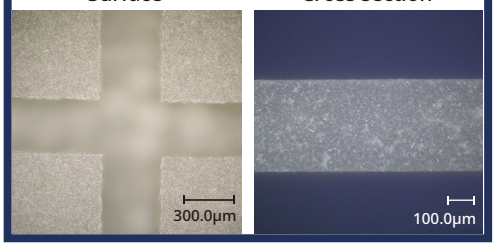
Material	: AlN
Thickness	: t0.635 mm
Substrate size	: 100 mm x 100 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

Surface / Cross section



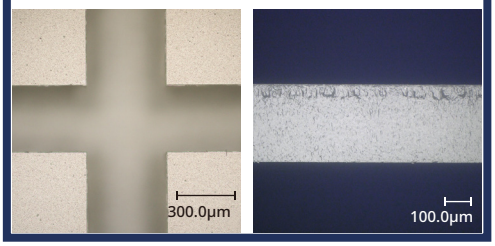
Material	: Si_3N_4
Thickness	: t0.32 mm
Substrate size	: 100 mm x 100 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

Surface / Cross section



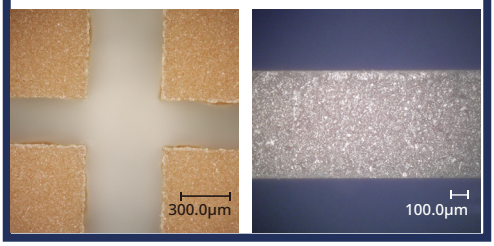
Material	: ZrO_2(YSZ)
Thickness	: t0.30 mm
Substrate size	: 100 mm x 100 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

Surface / Cross section



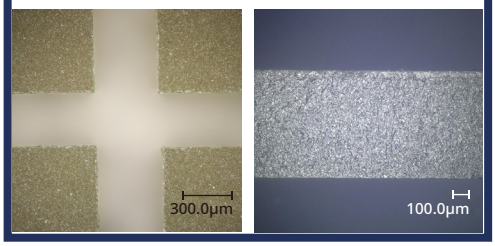
Material	: 誘電体 εr20.5
Thickness	: t0.635 mm
Substrate size	: 50 mm x 50 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

Surface / Cross section



Material	: 誘電体 εr134
Thickness	: t0.635 mm
Substrate size	: 50 mm x 50 mm
Chip size	: 5.0 mm x 5.0 mm
Process	: Scribing wheel

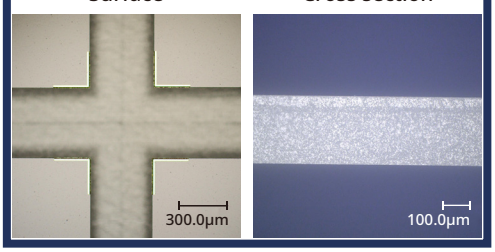
Surface / Cross section



Metalized substrates

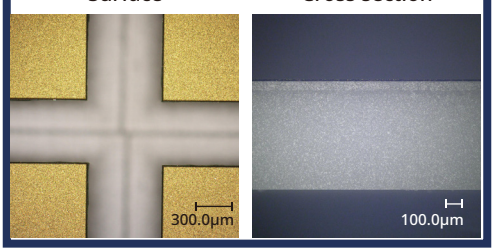
Material	: Al_2O_3 (With alignment mark)
Thickness	: t0.25 mm
Substrate size	: 76mm x 76 mm
Chip size	: 10.0 mm x 10.0 mm
Process	: Scribing wheel

Surface / Cross section



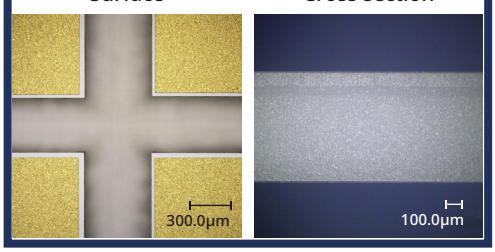
Material	: Al_2O_3 (With one side metal)
Thickness	: t0.635 mm
Substrate size	: 76 mm x 76 mm
Chip size	: 10.0 mm x 10.0 mm
Process	: Scribing wheel

Surface / Cross section



Material	: Al_2O_3 (With dual sided metal)
Thickness	: t0.635 mm
Substrate size	: 76 mm x 76 mm
Chip size	: 10.0 mm x 10.0 mm
Process	: Scribing wheel

Surface / Cross section



※表面写真は切断後、エキスパンドした状態です。